

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

PIC Packaging: Securing Optimal Integration and Performance

09:00 **Electrooptic Glass Substrates for Photonic Packaging**

Presented by Andreas Matiss - Corning

09:15 **Industry proven Photonic Wire Bonds and Facet-Attached Micro-Optical Elements: from Telecom/Datacom to Quantum Applications**

Presented by Philipp-Immanuel Dietrich - Vanguard Automation

09:30 **Optimizing Cost and Scaling Efficiency in Swept Wavelength Testing for Alignment and Packaging of PIC**

Presented by Matt Adams - VIAVI Solutions

09:45 **Advancing Optical Testing for Photonic Integrated Circuits: From Prototype to Production Scale-Up**

Presented by Ricardo Arias - Luna Innovations

10:00 **Towards a Comprehensive, Multiphysics Design Solution for Co-packaged Optics**

Presented by Ahsan Alam - Ansys Optics

10:15 **Aligned additive microfabrication for advanced optical packaging**

Presented by Jochen Zimmer - Nanoscribe

10:30 Morning Break

11:00 **Breaking the barriers for high frequency packaging**

Presented by Guillermo Carpintero - LEAPWAVE TECHNOLOGIES

11:15 **Technology Developments & Equipment Concepts for Scaling Up Photonics Production for Datacenters**

Presented by Malte Ennen - ficonTEC

11:30 **As Photonics Applications Multiply, New Ways to Subtract Costs**

Presented by Scott Jordan - Physik Instrumente

11:45 **Advances in PIC Manufacturing for Sensing and Datacom Applications – ALL Thanks to Nanoimprint Lithography**

Presented by Jonas Khan - EV Group

12:00 **AIM Photonics Foundry providing Co-Process and Co-Development to Address Challenges in Photonic Integrated Circuit (PIC) Packaging**

Presented by David Harame - AIM Photonics

12:15 **Impact of PIC device architecture and integration concept on packaging and assembly**

Presented by Helen Waechter - Helbling Technik Bern AG

12:30 **Advancing the Frontier of Photonic Integration: Challenges and Innovations in PIC Packaging**

PHIX, Lightwave Logic Inc, Tyndall National Institute, and POET Technologies

13:00 Lunch Break

Hybrid PICs: Pioneering New Frontiers in Photonic Integration

Sponsored by OPTICA

14:15 **Designing high power hybrid integrated tuneable lasers for automotive LiDAR**

Presented by Ruud Oldenbeuving - imec

14:30 **Advances in hybrid Silica-Nitride waveguides**

Presented by Henk Bulthuis - Broadex Technologies

14:45 **Unlocking the potential of hybrid/heterogeneous PIC design**

Presented by Martin Fiers - Luceda Photonics

15:00 **TFLN PIC Platform: Unleashing Monolithic power to Enhance Hybrid/Heterogeneous PICs**

Presented by Hamed Sattari - CSEM

15:15 **High speed, low power, tiny modulators in a polymer PIC platform are poised to enable 800G/1.6Tbps data communications, driven in part by artificial intelligence.**

Presented by Michael Lebby - Lightwave Logic Inc

15:30 **Advanced Photonic Integrated Circuit Testing: APEX Technologies' solution for High Precision Optical Instrumentation**

Presented by Tomy Marest - APEX Technologies

15:45 **BTO-powered PICs for communication and switching**

Presented by Cyriel Minkenberg - Lumiphase

16:00 Afternoon Break

16:30 **Heterogeneous integration to capitalize on upcoming markets, the new IPSR-I global roadmap update**

Presented by Peter van Arkel - PhotonDelta

16:45 **Advancements in Optically Enhanced MEMS Inertial Sensors: Prototyping and Roadmap Challenges for Consumer Markets (Video presentation)**

Presented by Lia Li - Zero Point Motion

17:00 **Augmented Silicon Photonics for demanding Data Center and AI/ML network fabrics**

Presented by Yannick Paillard - SCINTIL Photonics

- 17:15** **Silicon-organic hybrid electro-optic modulators for next generation optical interconnects**
Presented by Adrian Mertens - SilOrix
- 17:30** **Heterogeneous Integration of Photonic Devices on Silicon**
Presented by Jonathan Klamkin - UCSB (University of California Santa Barbara)
- 17:45** **Photonic Integrated Circuits: Surface Coupling Lasers using InP as an integration platform**
Presented by Bill Ring - Vector Photonics
- 18:00** **Sputter deposited Al₂O₃: an ultra-low loss integrated photonic platform for broadband operation from the UV till the mid-IR**
Presented by Sonia M. Garcia-Blanco - ALUVIA Photonics
- 18:15** **Closing Remarks**
- 18:20** **Networking Drinks / Dinner Reception**

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Rapid Scaling: Foundries Fuelling PICs' Mass Production

09:00 **A view from the Foundry: Silicon Photonics**

Presented by Anthony Yu - GlobalFoundries

09:15 **Low Loss Photonic Integrated Circuits: From Prototype to Volume**

Presented by Michael Geiselmann - LIGENTEC

09:30 **Silicon photonics for AI/HPC Optical Interconnects**

Presented by Philippe Absil - imec

Power Efficiency: Minimizing Consumption in PICs

09:45 **The evolving role of optics in AI Clusters**

Presented by Vlad Kozlov - LightCounting

PIC Size and Simulation: Enhancing Design Efficiency

10:00 **A perspective on recent trends in inverse design of integrated photonic devices and circuits**

Presented by Wolfer Peelaers - Hewlett Packard Enterprise

10:15 **Efficient design techniques for custom PDKs protecting your IP**

Presented by Andrzej Pożatynski - VPIphotonics

10:30 Morning Break

Accelerating PIC Adoption in Established Markets

Sponsored by LioniX International

11:10 **Design to Device: Accelerating PIC adoption by lowering entry barriers to turnkey photonic solutions**

Presented by Amitesh Singh - LioniX

11:25 **Transforming point-of-care diagnostics: The power of silicon plasmonic biosensors in the battle against acute infections**

Presented by Dimitris Tsiokos - bialoom

11:40 **Is integrated optics a perfect fit for next generation of Access Networks?**

Presented by Prof. Dr. Antonio Teixeira - PICadvanced

11:55 **Innovate with Confidence: Strategies for reliable PIC design**

Presented by Ronald Broeke - Bright Photonics

12:10 **Scaling photonic integration and packaging of hybrid multi-chip assemblies using 3D lithography**

Presented by Dr. Laura Horan - Vanguard Automation

12:25 **Opportunities for Photonics in Datacenter and High-Performance Computing (HPC) Infrastructure**

Presented by Remco Stoffer - Synopsys

12:40 Lunch Break

13:55 **Silicon Photonics Market and Applications: from Optical Transceivers to Emerging Uses**

Presented by Eric Mounier - Yole Group

14:10 **Semiconductorization of Photonics using Silicon Optical Interposer**

Presented by Raju Kankipati - POET Technologies

14:25 **Efficient Test of PICs for High-Performance Computing Applications**

Presented by Daria Lavrova - Keysight Technologies

14:40 **Revolutionizing Architecture and Components for New Generation Energy-Efficient High-Density Photonic Integrated Coherent Transceivers**

Presented by Tomoyuki Akiyama - PETRA/Fujitsu

14:55 **Opportunities and Challenges for Optics in AI Factories**

Presented by Yannick De Koninck - NVIDIA

15:10 **PIC Solutions for Established and Novel Optical Communication Applications**

Presented by Mehrdad Ziari - Infinera

15:25 **Opportunities for Silicon Photonics: Developments and Applications**

Presented by James Falkiner - IDTechEx

15:45 Closing Remarks

NOTES

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